

UNITED STATES PATENT AND TRADEMARK OFFICE

BEFORE THE PATENT TRIAL AND APPEAL BOARD

SAMSUNG ELECTRONICS CO., LTD. AND
SAMSUNG ELECTRONICS AMERICA, INC.,

Petitioners,

v.

HARBOR ISLAND DYNAMIC, LLC,

Patent Owner.

Patent No. 9,147,609
Filing Date: March 8, 2012
Issue Date: September 29, 2015

Inventors: Hadi Jebory and David J. Howard
Title: THROUGH SILICON VIA STRUCTURE, METHOD OF
FORMATION, AND INTEGRATION IN SEMICONDUCTOR SUBSTRATE

**PATENT OWNER'S NOTICE OF
FILING DEMONSTRATIVE EXHIBITS**

Case No. IPR2024-01404

LISTING OF EXHIBITS

Exhibit No.	Description of Document
2001	Docket Control Order, Dkt. 38, in <i>Harbor Island Dynamic, LLC v. Samsung Elecs. Co.</i> , Case No. 2:24-cv-00140-JRG-RSP (E.D. Tex. Aug. 5, 2024)
2002	Order Denying Samsung’s Motion to Stay Pending <i>Inter Partes</i> Review, Dkt. 62, in <i>Harbor Island Dynamic, LLC v. Samsung Elecs. Co.</i> , Case No. 2:24-cv-00140-JRG-RSP (E.D. Tex. Dec. 19, 2024)
2003	Defendants’ Invalidity Contentions, served on September 26, 2024, in <i>Harbor Island Dynamic, LLC v. Samsung Elecs. Co.</i> , Case No. 2:24-cv-00140-JRG-RSP (E.D. Tex.)
2004	Merriam-Webster Dictionary definition for the word “taper.”
2005	Dictionary.com definition for the word “tapered.”
2006	Oxford English Dictionary definition for the word “tapered.”
2007	Transcript of June 17, 2025 Deposition of Dr. Scott E. Thompson
2008	<i>Thermal Stresses around Void in Through Silicon Via in 3D SiP</i> by T. Kinoshita, et al., published in the 2014 International Conference on Electronics Packaging (April 2014)
2009	<i>3D-interconnect: Visualization of Extrusion and Voids Induced in Copper-Filled Through-Silicon Vias (TSVs) at Various Temperatures Using X-Ray Microscopy</i> , by Kong et al., published in <i>Microelectronic Engineering</i> 92 (2012),
2010	<i>TSV Cu Filling Failure Modes and Mechanisms Causing the Failures</i> , by J.W. Choi, et al., published in <i>IEEE Transactions on Components, Packaging, and Manufacturing Technology</i> , Vol. 4, No. 4 (April 2014)

Exhibit No.	Description of Document
2011	<i>Low Stress TSV Arrays for High-Density Interconnection</i> , by Jiao, et al. (2022)
2012	Declaration of Mr. John Berg

Pursuant to 37 C.F.R. §42.6(e)(4)(ii) and the Board's Order Setting Oral Argument (Paper 25), Patent Owner Harbor Island Dynamic, LLC herewith submits the following Exhibit:

Exhibit No.	Description of Document
2013	Patent Owner's Demonstrative Exhibits

Respectfully submitted,

Dated: December 30, 2025 By: /Joseph M. Mercadante /
Joseph M. Mercadante (Reg. No. 64,077)
FABRICANT LLP
411 Theodore Fremd Avenue,
Suite 206 South
Rye, New York 10580
Tel. 212-257-5797
Fax. 212-257-5796
Email: jmercadante@fabricantllp.com

CERTIFICATE OF SERVICE

A copy of the foregoing Patent Owner's Notice of Filing Demonstrative Exhibits and Exhibit 2013 have been served on Petitioners' counsel of record as follows:

Joshua L. Goldberg
Email: joshua.goldberg@finnegan.com
Alexander E. Harding
Email: alexander.harding@finnegan.com
Chen Zang
Email: chen.zang@finnegan.com
**FINNEGAN, HENDERSON, FARABOW,
GARRETT & DUNNER, LLP**
901 New York Avenue NW
Washington, DC 20001-4413

Abhay A. Watwe
Email: abhay.watwe@finnegan.com
Biju I. Chandran
Email: biju.chandran@finnegan.com
**FINNEGAN, HENDERSON, FARABOW,
GARRETT & DUNNER, LLP**
1875 Explorer Street, Suite 800
Reston, VA 20190-6023

Shawn S. Chang
Email: shawn.chang@finnegan.com
**FINNEGAN, HENDERSON, FARABOW,
GARRETT & DUNNER, LLP**
271 17th Street, NW, Suite 1400
Atlanta, GA, 30363-6209

*Attorneys for Samsung Electronics Co., Ltd.;
Samsung Electronics America, Inc.*

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PATENT NO. 9,147,609

December 30, 2025

By: /Joseph M. Mercadante
Joseph M. Mercadante (Reg. No. 64,077)
Lead Counsel for Patent Owner